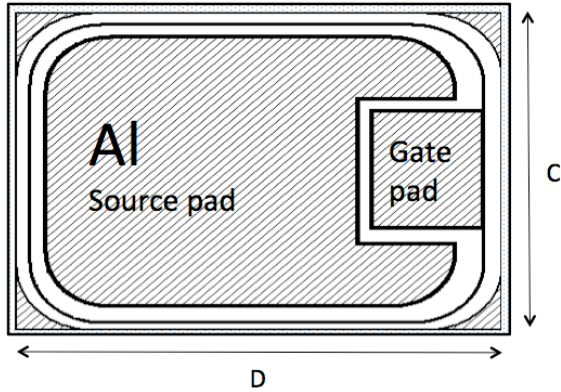
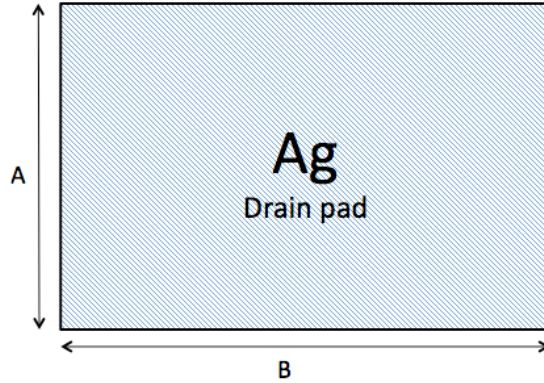


Chip Features

Front side



Back side



Chip Size (um)	Thickness (um)	Pad Size-Gate (um)	Pad Size-Source (um)
3,480 * 2,680	350	430 * 550	1,000 * 2,000

Referenced PKG Electrical Ratings TC = 25°C unless otherwise noted

Characteristics (Tc=25°C, unless otherwise specified)

Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics					
BVDSS	VGS=0, ID=250μA	400	-	-	V
IDSS	VDS =400V, VGS =0V	-	-	1	uA
IGSSF	VGS =30V, VDS =0V	-	-	100	nA
IGSSR	VGS =-30V, VDS =0V	-	-	-100	nA
VGS	VDS = VGS, ID=250μA	2.0	-	4.0	V
*RDS(ON)	VGS =10V, ID =3.0A	-	0.9	1.0	mΩ